



50V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(ON)} Max	I _D Max T _A = +25°C
50V	15mΩ @ V _{GS} = 10V	9.1A
50 V	$23m\Omega @ V_{GS} = 4.5V$	7.4A

Description and Applications

This MOSFET is designed to minimize the on-state resistance $(R_{DS(ON)})$, yet maintain superior switching performance, making it ideal for high efficiency power management applications.

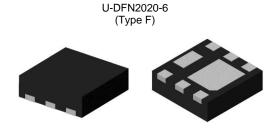
- Load Switch
- Adaptor Switch
- Notebook PC

Features

- 0.6mm Profile Ideal for Low Profile Applications
- PCB Footprint of 4mm²
- Low Gate Threshold Voltage
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

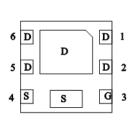
Mechanical Data

- Case: U-DFN2020-6 (Type F)
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 ⁶⁴
- Weight: 0.007 grams (Approximate)

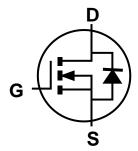


Top View

Bottom View



Pin Out Bottom View



Internal Schematic

Ordering Information (Note 4)

Part Number	Marking	Reel Size (inches)	Quantity per Reel
DMT5015LFDF-7	T5	7	3,000
DMT5015LFDF-13	T5	13	10,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



T5 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: D = 2016) M = Month (ex: 9 = September)

Date Code Key

Year	201	6	2017		2018	20	19	2020		2021	2	2022
Code	D		Е		F	(3	Н				J
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units		
Drain-Source Voltage	V _{DSS}	50	V		
Gate-Source Voltage	V _{GSS}	±16	V		
Continuous Dusin Courset (Note CVV 40V	Steady State	$T_A = +25$ °C $T_A = +70$ °C	I _D	9.1 7.3	А
Continuous Drain Current (Note 6) V _{GS} = 10V	t<10s	$T_A = +25$ °C $T_A = +70$ °C	I _D	11.5 9.2	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I _{DM}	60	Α		
Continuous Source-Drain Diode Current	Is	2.2	А		
Avalanche Current (Note 7) L = 0.1mH	I _{AS}	14.4	А		
Avalanche Energy (Note 7) L = 0.1mH	E _{AS}	10.4	mJ		

Thermal Characteristics

Characteristic	Symbol	Value	Units		
Total Bawar Dissination (Note 5)	$T_A = +25^{\circ}C$	C	0.82	W	
Total Power Dissipation (Note 5)	$T_A = +70^{\circ}C$	P_{D}	0.52	VV	
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	0	153	°C/W	
memai Resistance, Junction to Ambient (Note 5)	t<10s	$R_{\theta JA}$	96	C/VV	
Total Power Dissipation (Note 6)	$T_A = +25^{\circ}C$	C	1.97	W	
Total Power Dissipation (Note 6)	$T_A = +70^{\circ}C$	P_{D}	1.2		
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	C	67	°C/W	
Thermal Resistance, Junction to Ambient (Note 6)	t<10s	$R_{\theta JA}$	42		
Thermal Resistance, Junction to Case (Note 6)	Steady State	$R_{ heta JC}$	14		
Operating and Storage Temperature Range		T _{J,} T _{STG}	-55 to +150	°C	

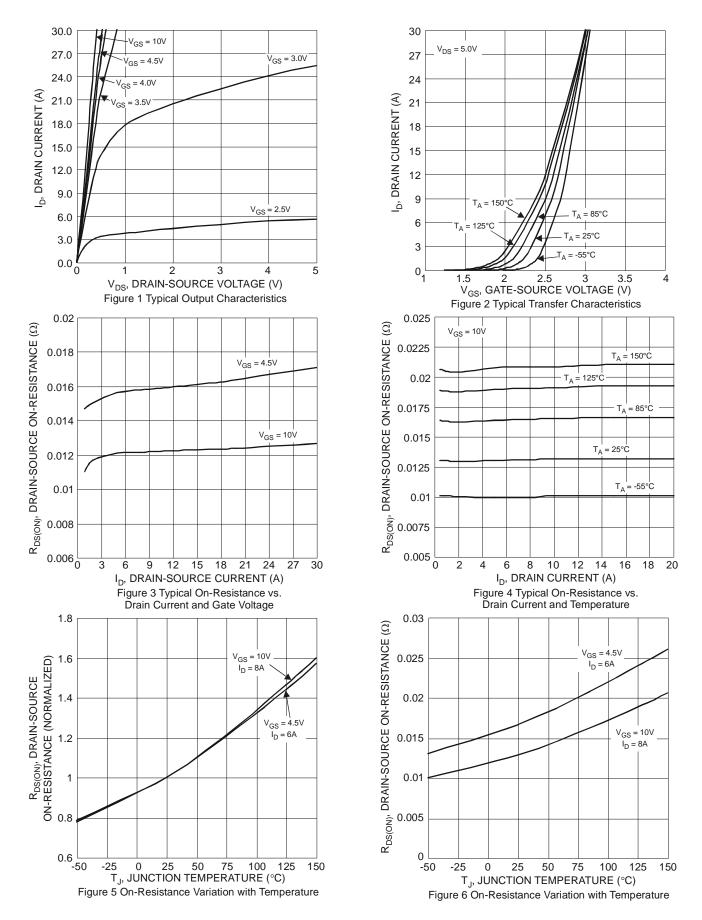
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Drain-Source Breakdown Voltage	BV _{DSS}	50	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	_	_	1	μA	$V_{DS} = 40V, V_{GS} = 0V$
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 16V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	V _{GS(TH)}	0.5	_	2.0	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$
Static Drain-Source On-Resistance	В		10.5	15	mΩ	$V_{GS} = 10V, I_D = 8A$
Static Drain-Source On-Resistance	R _{DS(ON)}	_	14	23	11122	$V_{GS} = 4.5V, I_D = 6A$
Diode Forward Voltage	V _{SD}	_	0.7	1.0	V	$V_{GS} = 0V, I_{S} = 5A$
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	CISS	_	902.7	_		05)/)/ 01/
Output Capacitance	Coss	_	301.4	_	pF	$V_{DS} = 25V, V_{GS} = 0V,$ f = 1.0MHz
Reverse Transfer Capacitance	C _{RSS}	_	15.2	_		I = 1.0IVII IZ
Gate Resistance	R_{G}	_	1.9	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$
Total Gate Charge (V _{GS} = 4.5V)	Q_{G}	_	6.1	_		
Total Gate Charge (V _{GS} = 10V)	Q_{G}	_	14	_	nC	V _{DS} = 25V. I _D = 8A
Gate-Source Charge	Q_{GS}	_	2.4	_	IIC	V _{DS} = 25V, I _D = 6A
Gate-Drain Charge	Q_{GD}	_	1.6	_		
Turn-On Delay Time	t _{D(ON)}	_	2.8	_		
Turn-On Rise Time	t _R	_	5.1	_		$V_{DS} = 25V, V_{GS} = 10V,$
Turn-Off Delay Time	t _{D(OFF)}	_	10.6	_	ns	$R_G = 3\Omega$, $I_D = 8A$
Turn-Off Fall Time	t _F	_	2.7	_		
Reverse Recovery Time	t _{RR}		18.9	_	ns	I _F = 8A, di/dt = 100A/μs
Reverse Recovery Charge	Q _{RR}		9.2	_	nC	I _F = 8A, di/dt = 100A/μs

5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout. 6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

 ^{7.} IAS and EAS rating are based on low frequency and duty cycles to keep T_J = +25°C.
 8. Short duration pulse test used to minimize self-heating effect.
 9. Guaranteed by design. Not subject to product testing.







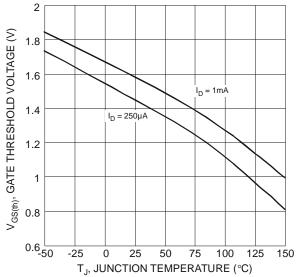


Figure 7 Gate Threshold Variation vs. Ambient Temperature

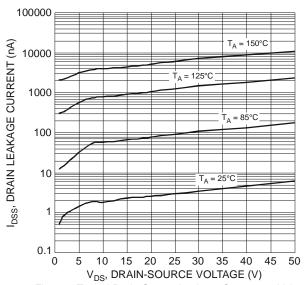
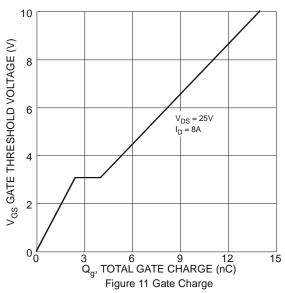
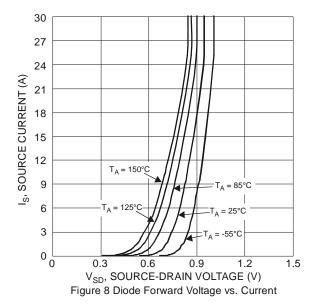
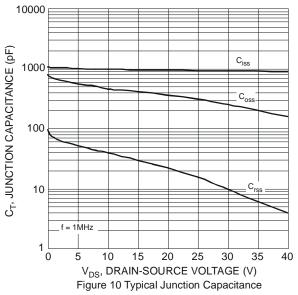
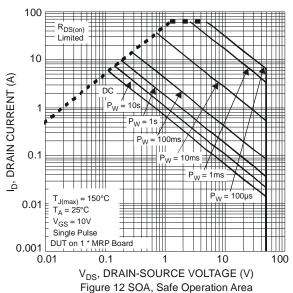


Figure 9 Typical Drain-Source Leakage Current vs. Voltage





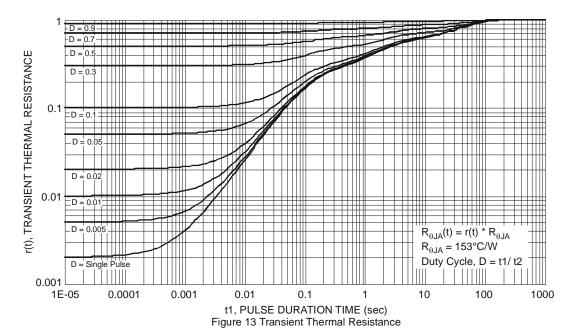




July 2016

© Diodes Incorporated



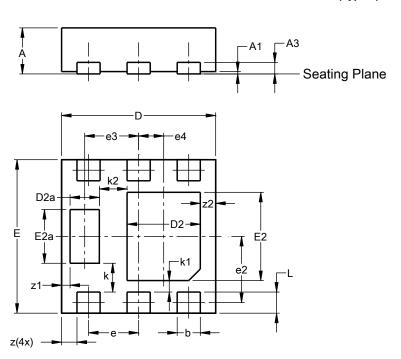




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2020-6 (Type F)

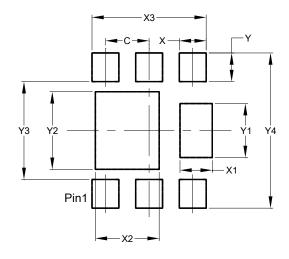


U-DFN2020-6 (Type F)						
Dim	Min	Max	Тур			
Α	0.57	0.63	0.60			
A1	0.00	0.05	0.03			
А3	-	-	0.15			
b	0.25	0.35	0.30			
D	1.95	2.05	2.00			
D2	0.85	1.05	0.95			
D2a	0.33	0.43	0.38			
Е	1.95	2.05	2.00			
E2	1.05	1.25	1.15			
E2a	0.65	0.75	0.70			
е	0.65 BSC					
e2	0.863 BSC					
е3	0.70 BSC					
e4	0.325 BSC					
k	0.37 BSC					
k1	0.15 BSC					
k2	0.36 BSC					
L	0.225 0.325 0.275					
Z	0.20 BSC					
z 1	0.110 BSC					
z2	0.20 BSC					
All Dimensions in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2020-6 (Type F)



Dimensions	Value
	(in mm)
С	0.650
X	0.400
X1	0.480
X2	0.950
Х3	1.700
Y	0.425
Y1	0.800
Y2	1.150
Y3	1.450
Y4	2.300



IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes Incorporated.

LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

- A. Life support devices or systems are devices or systems which:
 - 1. are intended to implant into the body, or
 - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2016, Diodes Incorporated

www.diodes.com